

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1539699	(stack\$5 mount\$5 plural\$4 multi\$3 first second upper lower top bottom) with (semiconductor die dice chip ic electronic (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 19:37
L2	19816	1 same ((adhes\$5 insulat\$5) with (particle stuff\$4 fill\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 19:39
L3	5906	2 and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 19:40
L4	5085	(structure module packag\$4) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 19:41
L5	2088	((non with (spher\$6 circle cirular)) contour prolat\$4 spher\$6 rectangular) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 19:48